

Silicon Carbide Power MOSFET

C3M™ MOSFET Technology

N-Channel Enhancement Mode

Features

- 3rd generation SiC MOSFET technology
- Optimized package with separate driver source pin
- High blocking voltage with low on-resistance
- High-speed switching with low capacitances
- Fast intrinsic diode with low reverse recovery (Q,,)
- Halogen free, RoHS compliant

Benefits

- Reduce switching losses and minimize gate ringing
- Higher system efficiency
- Reduce cooling requirements
- Increase power density
- Increase system switching frequency

Typical Applications

- Datacenter Power Supplies
- Telecom Power Supplies
- Energy Storage Systems
- Solar (PV) inverters
- High Voltage DC/DC converters

Package

Drain Tab







12345678

		(TAB)
Gate (Pin 1)	₩ H	
	Driver Source (Pin 2)	Power Source (Pin 3,4,5,6,7,8)

Orderable Part Number		Package	Marking		
	C3M0025065L-TR	TOLL	C3M0025065L		

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Key Parameters

Parameter	Symbol	Min.	Тур.	Max	Unit	Conditions	Note	
Drain - Source Voltage	V _{DS}			650		T _c = 25°C		
Maximum Gate - Source Voltage	V _{GS(max)}	-8		+19	v	Transient		
Operational Gate-Source Voltage	V _{GS op}		-4/15			Static	Note 1	
				77	A	$V_{GS} = 15 \text{ V}, T_{C} = 25 \text{ °C}, T_{J} \le 175 \text{ °C}$	Fig. 19	
DC Continuous Drain Current	l I _D			59		$V_{GS} = 15 \text{ V}, T_{C} = 100 \text{ °C}, T_{J} \le 175 \text{ °C}$	Note 2	
Pulsed Drain Current	I _{DM}			235		t _{Pmax} limited by T _{jmax} V _{GS} = 15V, T _C = 25 °C	Fig. 22	
Power Dissipation	P _D			326	W	$T_{c} = 25 ^{\circ} \text{C}, T_{J} = 175 ^{\circ} ^{\circ} ^{\circ}$	Fig. 20	
Operating Junction and Storage Temperature	T _J , T _{stg}			-40 to +175	°C			
Solder Temperature	T _L			260		According to JEDEC J-STD-020		

Note (1): Recommended turn-on gate voltage is 15V with ±5% regulation tolerance, see Application Note PRD-04814 for additional details Note (2): Verified by design

Electrical Characteristics (T_c = 25°C unless otherwise specified)

Symbol	Parameter	Min.	Тур.	Max.	Unit	Test Conditions	Note	
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	650			٧	V _{GS} = 0 V, I _D = 100 μA		
.,	Gate Threshold Voltage	1.8	2.3	3.6	V	V _{DS} = V _{GS} , I _D = 9.22 mA	Fig. 11	
$V_{\text{GS(th)}}$			1.9		V	V _{DS} = V _{GS} , I _D = 9.22 mA, T _J = 175°C		
I _{DSS}	Zero Gate Voltage Drain Current		1	50	μA	V _{DS} = 650 V, V _{GS} = 0 V		
I_{GSS}	Gate-Source Leakage Current		10	250	nA	V _{GS} = 15 V, V _{DS} = 0 V		
			25	34		V _{GS} = 15 V, I _D = 33.5 A	Fig. 4,	
R _{DS(on)}	Drain-Source On-State Resistance		33		mΩ	V _{GS} = 15 V, I _D = 33.5 A, T _J = 175°C	5, 6	
_	Tananandustana		24		S	V _{DS} = 20 V, I _{DS} = 33.5 A	F: 7	
g_{fs}	Transconductance		23		S	V _{DS} = 20 V, I _{DS} = 33.5 A, T _J = 175°C	Fig. 7	
C _{iss}	Input Capacitance		2970			V _{GS} = 0 V, V _{DS} = 400 V	Fig. 17, 18	
C_{oss}	Output Capacitance		186		pF	f = 1 Mhz		
C_{rss}	Reverse Transfer Capacitance		11		1	Vac = 25 mV		
E _{oss}	C _{oss} Stored Energy		18		μJ	V _{DS} = 400 V, f = 1 Mhz		
C _{o(er)}	Effective Output Capacitance (Energy Related)		226		pF	., .,,,	Note: 3	
$C_{o(tr)}$	Effective Output Capacitance (Time Related)		322		pF	V _{GS} = 0 V, V _{DS} = 0 400V		
Eon	Turn-On Switching Energy (Body Diode FWD)		123			$V_{DS} = 400 \text{ V, } V_{GS} = -4 \text{ V/15 V, } I_{D} = 33.5 \text{A,}$	Fig. 23	
E _{OFF}	Turn-Off Switching Energy (Body Diode FWD)		14		μJ	$R_{G(ext)} = 2.5 \Omega$, L= 59 μ H, $T_J = 25^{\circ}$ C FWD = Internal Body Diode		
$t_{d(on)}$	Turn-On Delay Time		10				Fig. 26	
t _r	Rise Time		13			$V_{DD} = 400 \text{ V}, V_{GS} = -4 \text{ V}/15 \text{ V}$ $I_D = 33.5 \text{ A}, R_{G(ext)} = 2.5 \Omega,$		
$t_{\text{d(off)}}$	Turn-Off Delay Time		26		ns	Timing relative to $V_{\scriptscriptstyle DS}$		
t _f	Fall Time		8			Inductive load		
$R_{\text{G(int)}}$	Internal Gate Resistance		1.3		Ω	f = 1 MHz, V _{AC} = 25 mV		
Q_{gs}	Gate to Source Charge		33			V _{DS} = 400 V, V _{GS} = -4 V/15 V		
Q_{gd}	Gate to Drain Charge		32		nC	I _D = 33.5 A	Fig. 12	
Q_g	Total Gate Charge		111			Per IEC60747-8-4 pg 21		

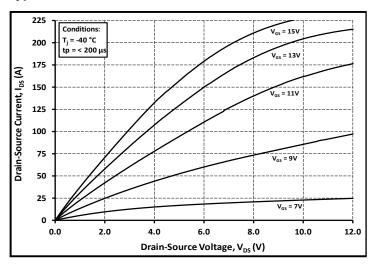
Note (3): C_{o(er)}, a lumped capacitance that gives same stored energy as Coss while Vds is rising from 0 to 400V C_{o(tr)}, a lumped capacitance that gives same charging time as Coss while Vds is rising from 0 to 400V

Reverse Diode Characteristics ($T_c = 25^{\circ}C$ unless otherwise specified)

Symbol	Parameter	Тур.	Max.	Unit	Test Conditions	Note
.,	Diode Forward Voltage	5.0		٧	$V_{GS} = -4 \text{ V, I}_{SD} = 16.8 \text{ A, T}_{J} = 25 \text{ °C}$	Fig. 8, 9, 10
V_{SD}		4.4		٧	$V_{GS} = -4 \text{ V, } I_{SD} = 16.8 \text{ A, } T_{J} = 175 ^{\circ}\text{C}$	
Is	Continuous Diode Forward Current		54	А	V _{GS} = -4 V, T _C = 25°C	
I _{S, pulse}	Diode pulse Current		235	Α	V_{GS} = -4 V, pulse width t_P limited by T_{jmax}	
t _{rr}	Reverse Recover time	14		ns		
Q _{rr} Reverse Recovery Charge		338		nC	$V_{GS} = -4 \text{ V, } I_{SD} = 33.5 \text{ A, } V_{R} = 400 \text{ V}$ dif/dt = 4717 A/µs, $T_{I} = 25 \text{ °C}$	
I _{rrm}	Peak Reverse Recovery Current	40		Α	. 3	
t _{rr}	Reverse Recover time	16		ns		
Q _{rr}	Reverse Recovery Charge	164		nC	V _{GS} = -4 V, I _{SD} = 33.5 A, V _R = 400 V dif/dt = 2137 A/μs, Τ, = 25 °C	
l _{rrm}	Peak Reverse Recovery Current	17		А	αιι/αι 210/7/μος ι 20 0	

Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Unit	Note
$R_{ heta JC}$	Thermal Resistance from Junction to Case	0.41	0.46	°C/W	



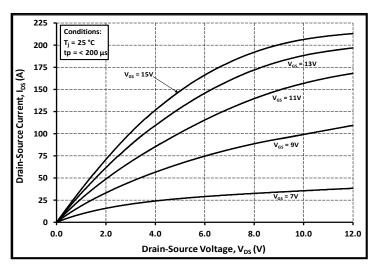
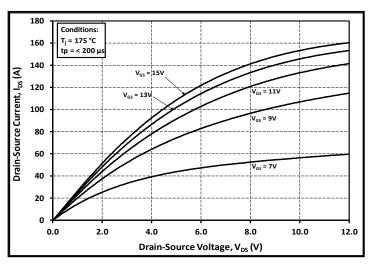


Figure 1. Output Characteristics T_J = -40 °C





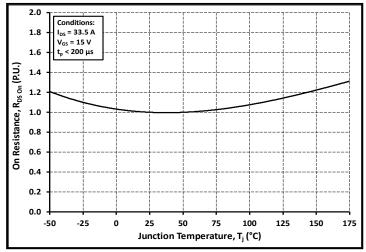
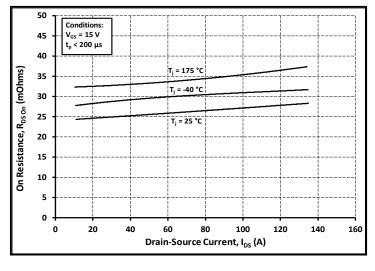


Figure 3. Output Characteristics T_J = 175 °C





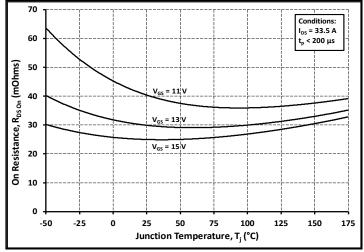
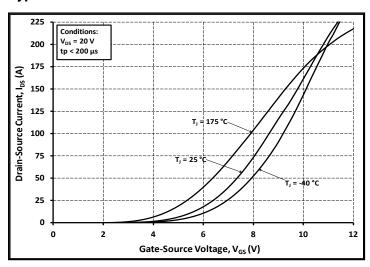


Figure 5. On-Resistance vs. Drain Current For Various Temperatures

Figure 6. On-Resistance vs. Temperature For Various Gate Voltage



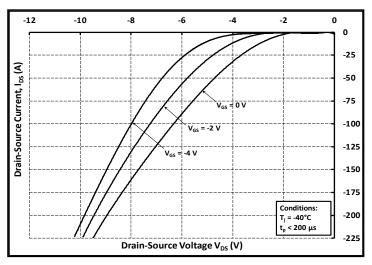
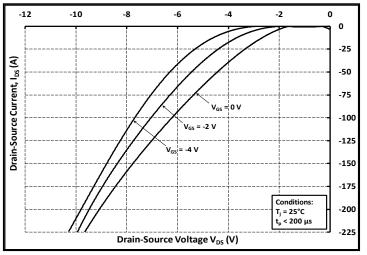


Figure 7. Transfer Characteristic for Various Junction Temperatures





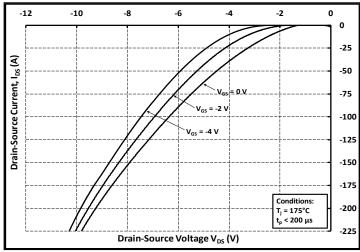
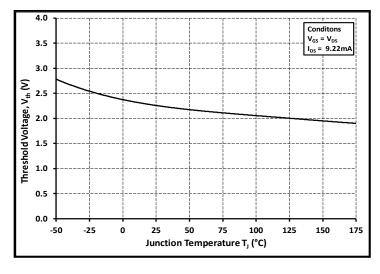


Figure 9. Body Diode Characteristic at 25 °C

Figure 10. Body Diode Characteristic at 175 °C



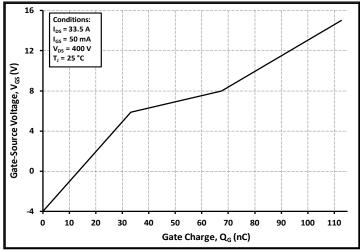
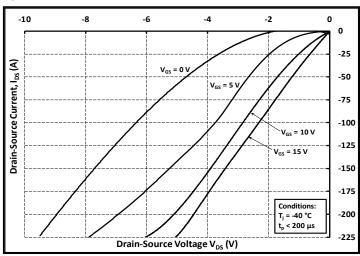


Figure 11. Threshold Voltage vs. Temperature

Figure 12. Gate Charge Characteristics



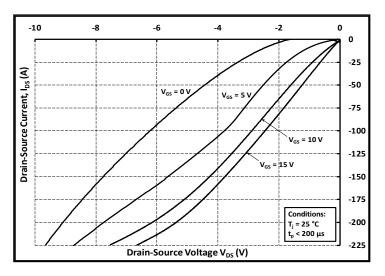
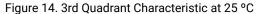
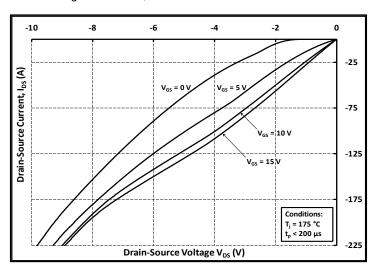


Figure 13. 3rd Quadrant Characteristic at -40 °C





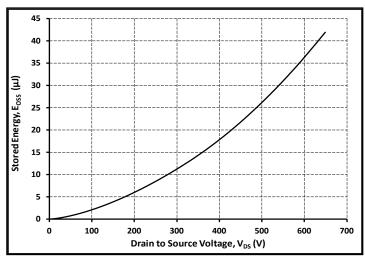
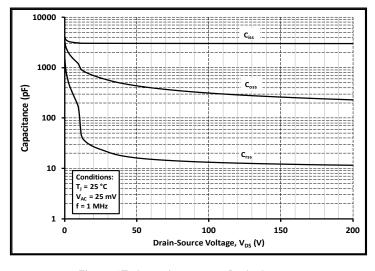


Figure 15. 3rd Quadrant Characteristic at 175 °C

Figure 16. Output Capacitor Stored Energy



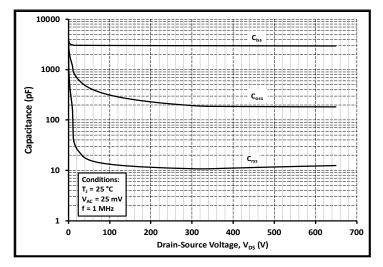
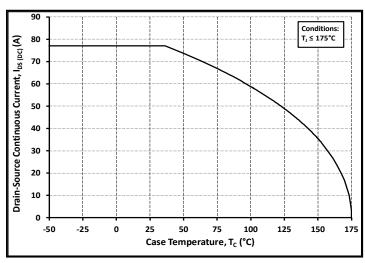


Figure 17. Capacitances vs. Drain-Source Voltage (0 - 200V)

Figure 18. Capacitances vs. Drain-Source Voltage (0 - 650V)



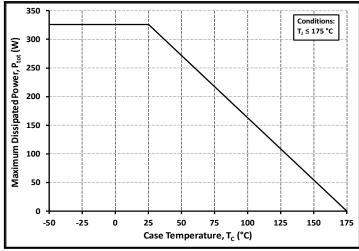
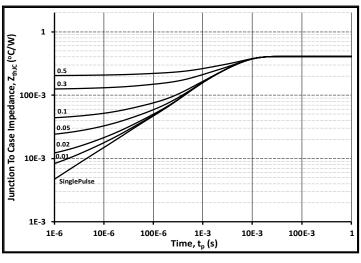


Figure 19. Continuous Drain Current Derating vs.

Case Temperature

Figure 20. Maximum Power Dissipation Derating vs.

Case Temperature



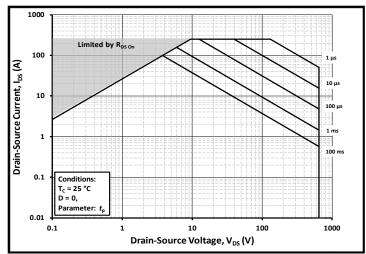
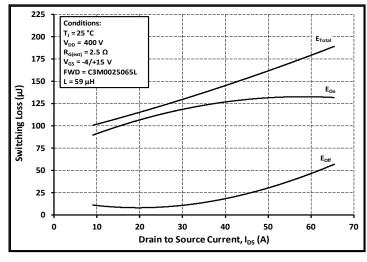


Figure 21. Transient Thermal Impedance (Junction - Case)

Figure 22. Safe Operating Area



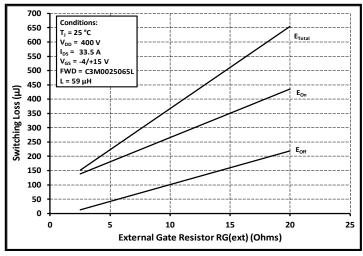


Figure 23. Clamped Inductive Switching Energy vs. Drain Current $(V_{DD} = 400V)$

Figure 24. Clamped Inductive Switching Energy vs. R_{G(ext)}

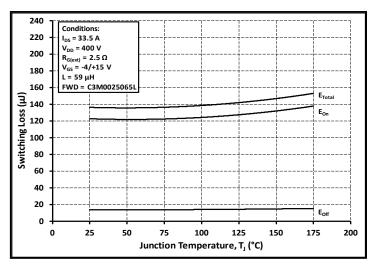


Figure 25. Clamped Inductive Switching Energy vs.
Temperature

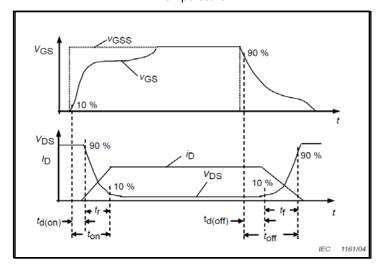


Figure 27. Switching Times Definition

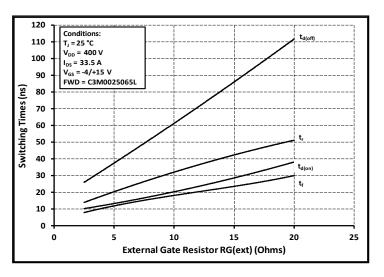


Figure 26. Switching Times vs. $R_{G(ext)}$

Test Circuit Schematic

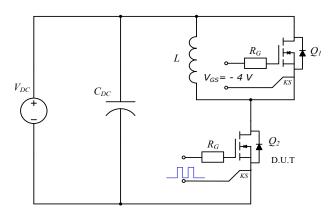
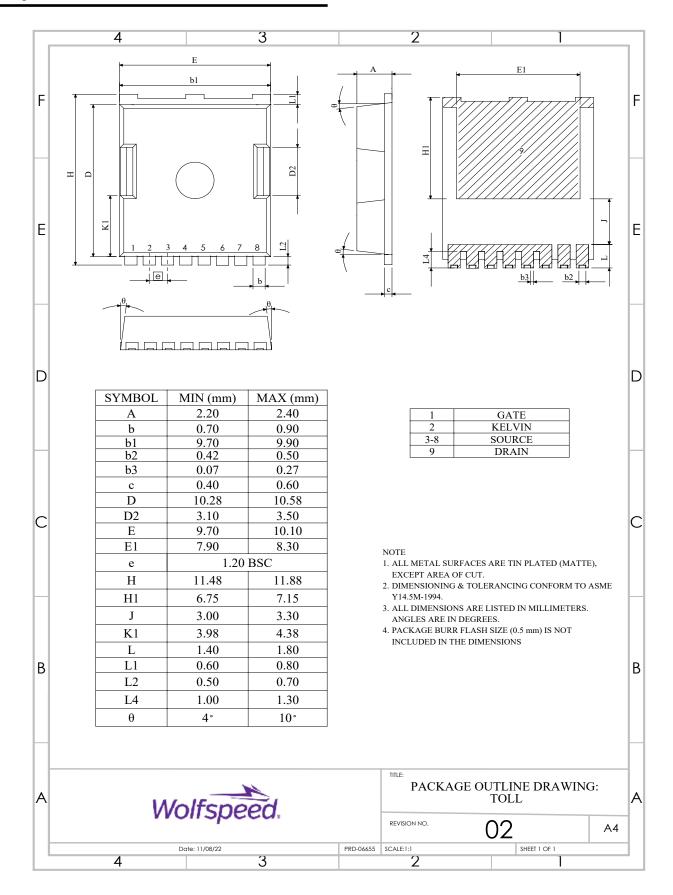


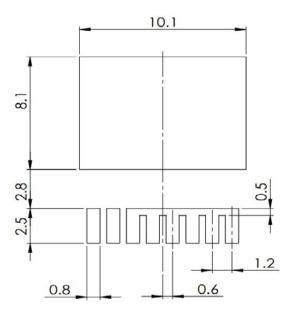
Figure 28. Clamped Inductive Switching Waveform Test Circuit

Package Dimensions



Recommended Solder Pad Layout

(Note: All Dimensions are listed in Millimeters)



Revision history

Document Version	Date of release	Description of changes
1	October-2022	Initial datasheet
2	December - 2024	Legal Disclaimer, Table 1 layout revised

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